

Product Change Notification - CYER-16OYZO526

Date: 22 Jun 2011 Product Category: Memory

Device Family: 图图

Notification subject: Addition of MTAI site packing materials for wafer sales of all SST device families.

Notification text:

PCN Status: Final notification

Microchip Catalog Part Numbers Affected:

See attachments of affected catalog part numbers (CPN) labeled as...

PCN_CYER-16OYZO526_Affected_CPN.xls PCN_CYER-16OYZO526_Affected_CPN.pdf

Description of Changes:

Addition of MTAI site packing materials for wafer sales of all SST device families.

Note: Please review the attached document for details titled PCN_CYER-16OYZO526_Packing Materials_Detail.pdf.

Impacts to Data Sheet:

None

Reason for Change:

Improve production cycle time and on-time delivery performance

Change Implementation Status:

Complete

Estimated First Ship Date:

June 28, 2011 (Date Code: 1127)

NOTE: Please be advised that after the estimated first ship date customers may receive wafers in existing or new packing material depending on inventory levels.

Markings to Distinguish Revised from Unrevised Devices:

Packing material

Revision History:

June 22, 2011: Issued final notification.

Attachment(s):

PCN_CYER-16OYZO526_Affected_CPN.pdf PCN_CYER-16OYZO526_Affected_CPN.xls

PCN_CYER-16OYZO526_Packing Materials_Detail.pdf

Please contact your local Microchip sales office with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to change your product/process change notification (PCN) profile please log on to our website at http://www.microchip.com/PCN sign into myMICROCHIP to open the myMICROCHIP home page, then select a profile option from the left navigation bar.

To opt out of future offer or information emails (other than product change notification emails), click here to go to microchipDIRECT and login, then click on the "My account" link, click on "Update profile" and un-check the box that states "Future offers or information about Microchip's products or services."

CYER-16OYZO526 - Addition of MTAI site packing materials for wafer sales of all SST device families.
Parts Affected
SST25VF010A
SST25VF016B
SST25VF040B
SST25VF080B
SST25VF512
SST25WF010
SST25WF040
SST26VF016
SST39VF020
SST39VF040
SST39VF1602
SST39VF400A
SST39VF800A
SST39WF1601
SST39WF400A
SST39WF400B
SST39WF800A
SST39WF800B

Date: Thursday, June 23, 2011